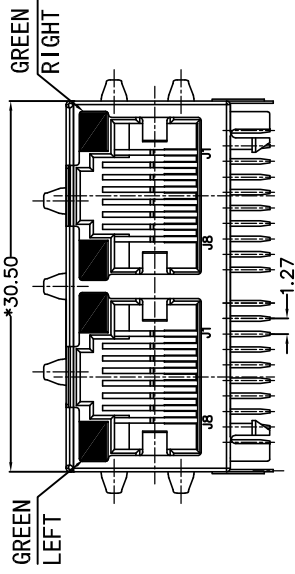
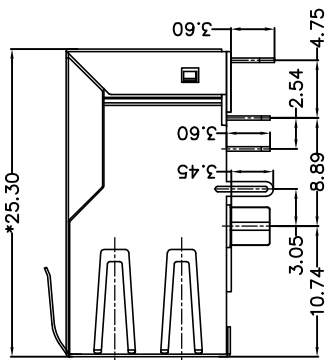


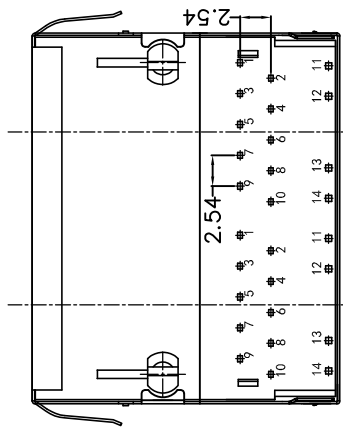
REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2018.05.30



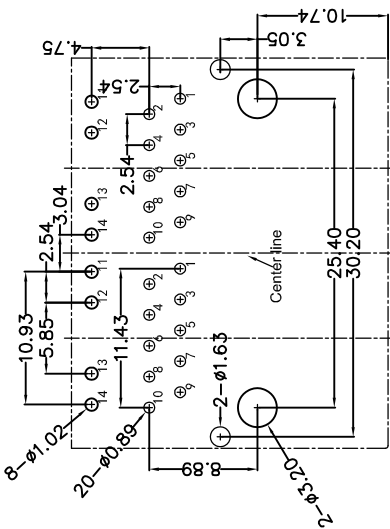
FRONT VIEW



RIGHT SIDE VIEW



BOTTOM VIEW



RECOMMENDED PCB LAYOUT
VIEWED FROM COMPONENT SIDE

MATERIAL:

HOUSING: PBT,UL94V-0,BLACK.
TERMINALS BRACKET: PBT,UL94V-0,BLACK.
SHIELD: C2680,T=0.20MM,NICKEL PLATING ON ALL AREA.
TERMINAL: PHOSPHOR BRONZE C5210,T=0.35MM,
6U" GOLD PLATING ON CONTACT AREA.

MECHANICAL:

DURABILITY: 750 CYCLES MIN.
MATING FORCE: 30N MAX.
OPERATING TEMPERATURE: -40°C~+85°C.
STORAGE TEMPERATURE: -40°C~+85°C.
ALL CRITICAL DIMENSIONS WITH "*"!

TITLE: TAB-UP 1X2 1000BASE		SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED	APPROVED BY: JP.Gong
PART NO.: FC-2546QNL		SACLE 1:1	REV A0	x±0.35 .x°±3.0°	CHECKED BY: TW.Xu
REMARK:		SHEET 1/3		.xx±0.25 .xxx°±1.5°	DESIGN BY: MQ.Qu
				.xxx±0.10 .xxx°±1.0°	

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1 2 3 4 5 6 7 8

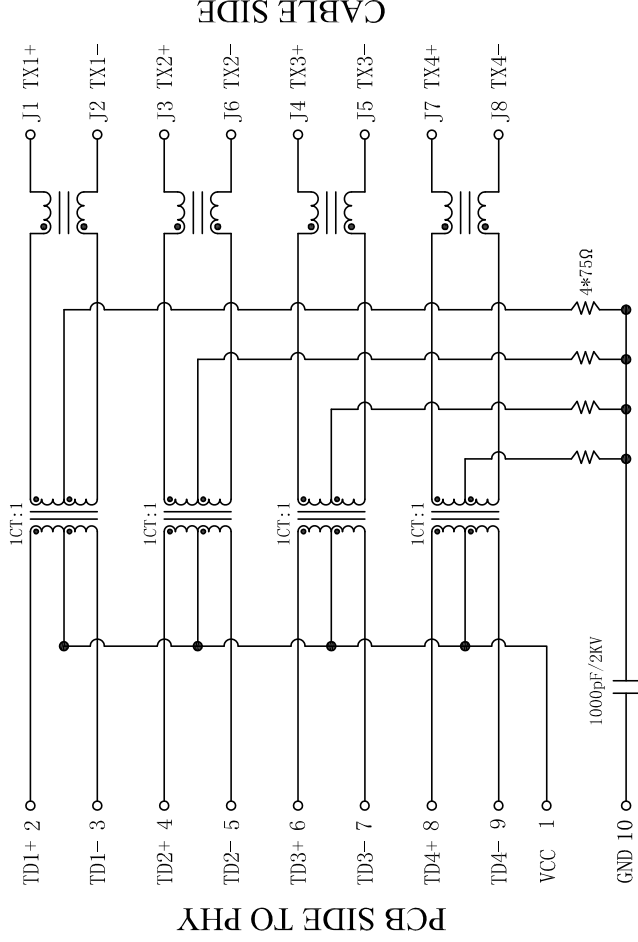
H G F E D C B A

1 2 3 4 5 6 7 8

H G F E D C B A

REACH & RoHS
COMPLIANT

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2018.05.30

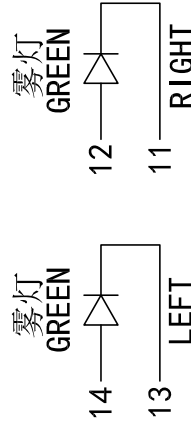


Electrical:

- Turn ratio: 2~3: J1~J2=1CT:1CT(±2%).
4~5: J3~J6=1CT:1CT(±2%).
6~7: J4~J5=1CT:1CT(±2%).
8~9: J7~J8=1CT:1CT(±2%).
- OCL: 350uH Min. at 100KHz 100mV 8mA DC.
- Insertion Loss: -1.0 dB Max 1~100MHz.
- Return loss: -20dB Min 1~10MHz;
-16dB Min 10~30MHz;
-12dB Min 30~60MHz;
-10dB Min 60~80MHz;
- Cross talk: -40dB Min 1~30MHz;
-35dB Min 30~60MHz;
-30dB Min 60~100MHz;
- CMR: -35dB Min 1~100MHz;
- Hi-Pot: 1500V AC & 2250V DC
6S 1mA PRI TO SEC

LED Specification

Standard LED Color	LED Wavelength	Forward(A)	Forward(V)
Green	568nm	20mA	1.85-2.45V



TITLE: TAB-UP 1X2 1000BASE		SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED	APPROVED BY: JP.Gong
PART NO.: FC-2546QNL		SACLE 1:1	REV A0	x±0.35 .x±0.30	CHECKED BY: TW.Xu
REMARK:		SHEET 2/3		.xx°±1.5° .xxx°±1.0°	DESIGN BY: MQ.Qu

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PROFILE OF WAVE SOLDER

The graph illustrates the temperature profile of wave soldering. The y-axis represents Temperature in degrees Celsius (°C), ranging from 20°C to 180°C. The x-axis represents Time in seconds (Sec.), with marked intervals of 60, 120, and 120. The profile is divided into three phases: A (Preheating), B (Soldering), and C (Gradual Cooling). Phase A shows a linear increase from 20°C to 120°C over 60 seconds. Phase B shows a peak at 180°C, maintained for 120 seconds. Phase C shows a linear decrease from 180°C to 20°C over 120 seconds.

Phase	Temperature (°C)	Time (Sec.)
A (Preheating)	20	0
	120	60
B (Soldering)	180	120
	180	240
C (Gradual Cooling)	180	360
	20	480

A.Preheating B.Soldering C.Gradual Cooling
 Tip temperature:260±5°C.
 Tip temperature time:5Sec Max.
 Tip melting point of Sn96.5/Ag3/Cu0.5:217°C.

Remarks: after wave soldering, the plastic positioning columns of the product which under the PCB will be slightly melted, but it won't affect its function.

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	MQ.Qu	2018.05.30

TITLE:	SIZE	UNITS	GENERAL TOLERANCES UNLESS SPECIFIED	APPROVED BY:
TAB-UP 1X2 1000BASE	A4	MM[INCH]	UNLESS SPECIFIED	JP.Gong

PART NO.:	SACLE	REV	GENERAL TOLERANCES UNLESS SPECIFIED	CHECKED BY:
FC-2546QNL	1:1	A0	x°±3.0° .x°±2.0°	TW.Xu

REMARK:	SHEET	DESIGNED BY:	GENERAL TOLERANCES UNLESS SPECIFIED	DESIGNED BY:
	3/3		.xx°±1.5° .xxx°±1.0°	MQ.Qu

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